LAPPD R&D Status Report

Alexander Kiselev (BNL) EIC PID Consortium meeting, October 17, 2022

Lab measurements at Brookhaven

Test bench setup



- Remotely controlled XYZ-stages
- 420nm pulsed "picosecond" laser (spot size <100 μm)
- A variety of multi-pattern pixelated readout boards



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here: all 3mm pitch

Test bench setup



- Light-tight enclosure
- 320 (soon 512) DRS4 channels (V1742 digitizers)
- MCX to high-density Samtec adapter cards



Modular setup: it takes one only half an hour to exchange (or rotate) the readout board

PCB stack details & cross-talk evaluation

are





- Multi-layer stack-up; through vias; isolated traces
- Worst case X-talk ~few % level



Spatial resolution with the 3 mm square pixels





8x8 field with 3mm pixels, connected to a pair of V1742s

- Gen II LAPPD tile #97 provided by Incom
 - 2mm thick ceramic base

Photo cathode	2375 V		
MCP#1 top	2300 V		
MCP#1 bottom	1375 V		
MCP#2 top	1175 V		
MCP#2 bottom	250 V		





Typical single photon cluster has RMS ~ 3.5 mm

6

2D zigzag pixels with a 6 mm pitch



Beam test at Fermilab in June 2021

(BNL, Incom Inc., Argonne, GSU, Stony Brook & other groups)

Experimental setup



The same setup as in the lab, but instead of a laser use *a thick aspheric lens* as a well controlled Cherenkov light source



Pixel pattern & accumulated single photon XY-coordinates





- Off-the-shelf component
- (Almost) no stray photons
- To first order no need in tracking
- The used model (Edmund Optics #67-265, EFL 20.0mm) produces a crisp ~76mm diameter ring at the focal plane



Cherenkov ring radius resolution



Single event with multiple photon clusters

 Yes, one can measure single Cherenkov photons with sub-mm spatial resolution using pixelated Gen II LAPPDs!

Paradigm change in the Cherenkov ring imaging data analysis: overlapping clusters rather than single pixel hits

Beam test at Fermilab in June 2022

(BNL, Incom Inc., Argonne, MSU, INFN Trieste)

Readout boards



An attempt to demonstrate a *simultaneous* ring imaging and time-of-flight performance

Experimental setup

• G1 .. G4 – COMPASS GEM reference tracker



- A new 20 cm Gen II LAPPD tile 136
 - 10 μm pore MCPs
 - Full glass body (implies 5 mm thick anode base plate)
 - Window material -> UV grade quartz
- GEM reference tracker
- New set of the pixelated readout boards
- A pair of Planacon MCP-PMTs as a timing reference

Enough data on tape to quantify **single-photon** timing resolution

Aspheric lens as a source of coherent Cherenkov photons



Single events: no filter, 24x24 4mm pixel field, [mV] units 13

A quest for <10 ps timing for TOF applications

LAPPD quartz window as a Cherenkov radiator



Due to the TIR, photons only hit the PC in a radial band ~[5.5 .. 12.0] mm



Single photon TTS ~50 ps

Number of event

20

UV grade quartz window: a 120 GeV proton produces a blob of ~100 p.e.'s





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work:

Future

DRS4 chip#1: time(ch#15) – time(ch#13)

Beam test at CERN in October 2022

(INFN Trieste, INFN Genoa, Incom Inc., BNL)

Experimental setup at CERN in October 2022



- A standard 20 cm Gen II LAPPD tile 124 with 20 μm pore MCPs
- Incom's own 8x8 pad board
- x10 amplifier boards
- Hamamatsu MCP-PMTs as a timing reference





Other news



- October 26, 2022, second one in the series: <u>https://indico.bnl.gov/event/17475/</u>
- The first workshop (<u>https://indico.bnl.gov/event/15059/</u>) happened in March 2022
 - Attended by 80+ participants
 - Talks by Incom, Nalu Scientific, NP/HEP research groups

- Stony Brook / Brookhaven Seed Grant proposal "LAPPDs for TOF PET: a breakthrough in ultra-high sensitivity Positron Emission Tomography using fast affordable Micro-Channel Plate photomultipliers" was approved and started in July 2022 (Amir Goldan & AK)
 - Quite some synergy with the HEP/NP LAPPD R&D activities

DC-coupled HRPPD interface

DC-coupled HRPPD



Tile #4 delivered to BNL two weeks ago



- ~120 x 120 mm² footprint; ~100x100 mm² active area (no spacers); 1/8" (~3.2 mm) pad pitch
- Short MCP stack with 5mm thick quartz window and 3mm thick ceramic base plate

Dual purpose readout PCB



- A compact universal 132 x 132 mm² board
- Pixellation follows ~3.2mm HRPPD pad pitch
- Two "main" instrumentation options:
 - A 16x16 pad field in the center
 - Pairs of individual pad fields for systematic studies
- Connectivity via either MCX->MCX cables or Samtec->MCX adapters
- Can be used for the DC-coupled HRPPDs (assembly with the pogo pins), as well as for the capacitively coupled HRPPDs / LAPPDs (assembly without the pogo pins)
- Can also be used in a coincidence setup with a picosecond laser

Bare boards will be shipped to BNL end of the month

3D integration model (here: a 16x16 pad PET setup)



3D integration model (for systematic studies)



 Several pairs of spots with different pad and trace configurations and connections to MCX cables implemented

Laser-based timing evaluation setup



- Alternatively, use PHOTONIS single anode MCP-PMT as a timing reference
- Alternatively, consider a femtosecond laser

Summary & FY23 Outlook

- Proof of principle measurements confirming feasibility of Gen II LAPPD use for single photon detection in Cherenkov imaging applications are performed in the test bench setup and with a particle beam; *spatial resolution* quantified, looks satisfactory ...
 - ... and can only become better once the preamplifiers are used
- *Timing performance* in a finely pixelated configuration requires more work
 - DRS4 calibration (by now have two independent *almost* working procedures / codes)
 - Existing beam test data analysis
 - Back to the bench top evaluation ... then another beam test at Fermilab and / or at CERN
- DC-coupled HRPPD performance evaluation
 - A better mechanical / electrical interface may be required
- Work on practical LAPPD / HRPPD applications for EIC detectors
 - pfRICH, mRICH, ..?
 - On-board electronics integration

Backup: a draft of Gen II HRPPD-for-pfRICH 3D model



- Assume 24x24 pixellation suffices (~4.2mm pads) -> 576 pixels per 12x12 cm² footprint
- A hybrid of Nalu Scientific UDC and AARDVARC v4 chips assumed as a "reference ASIC"
 - 16-channel ASICs (would be better to have 32- or 64-channel ones, of course)
 - 20dB preamplifier on die (~6mW additional power per channel)
 - ~10GS/s digitizer, ~2GHz ABW, feature extraction, streaming capability (whatever it means), etc.
 - Few kW of power dissipation for the whole system seems to be a real-life estimate